



App. No. 09/274,194

#14  
11/19/02

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

5 In re application of: ) Docket No: LAM2P266  
John E. LANG )  
Application No: 09/274,194 ) Group Art Unit: 1765  
10 Filed: October 16, 2001 ) Examiner: C. Brown  
For: METHOD OF REMOVING PHOTORESIST )  
MATERIAL WITH DYMETHYL SULFOXIDE )  
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CERTIFICATE OF MAILING  
I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail addressed to: Commissioner for Patents, Washington, DC 20231 on November 7, 2002.  
Signed: Kay Harlow  
Kay Harlow

RESPONSE TO OFFICE ACTION

Commissioner for Patents  
Washington, D.C. 20231

Dear Sir:

This is in response to the Office Action dated July 8, 2002. The period of response extends to November 8, 2002, with one-month extension of time. Please enter the following remarks:

REMARKS

The Examiner is thanked for the careful review of this Application. Claims 20 - 38 are pending.

Rejections under 35 U.S.C. § 103(a)

It is respectfully submitted that claims 20 - 38 are patentable over U.S. Patent No. 6,066,569 to Tobben in view of U.S. Patent No. 5,399,202 to Kikuchi et al.

Tobben teaches a process for manufacturing silicon integrated circuits including an organic intermetal dielectric using a dual damascene metallization process. In Tobben, a layer of intermetal dielectric is provided over the top surface of a work piece subsequent

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